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### **IN THE CLAIMS:**

Please substitute the following claims for the previous claims:

1. (Currently Amended) A substrate processing chamber component capable of being exposed to a plasma in a process chamber, the component comprising:

(a) a substrate processing chamber component structure; and  
(b) an electroplated coating on the substrate processing chamber component structure, the electroplated coating comprising yttrium-containing species, and the electroplated coating formed by:

(i) immersing the surface of the component structure in an electroplating bath comprising a solution of yttrium species;

(ii) connecting the component structure to a negative terminal of a voltage source; and

(iii) connecting an anode immersed in the bath to a positive terminal of the voltage source.

2. (Original) A component according to claim 1 wherein the yttrium-containing species comprises one or more of elemental yttrium and yttrium oxide.

3. (Original) A component according to claim 1 wherein the yttrium-containing species comprises yttrium oxide, and wherein the electroplated coating further comprises aluminum oxide or zirconium oxide.

4. (Previously Presented) A component according to claim 3 wherein the electroplated coating comprises a compound comprising yttrium oxide and aluminum oxide.

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5. (Original) A component according to claim 3 wherein the electroplated coating comprises partially stabilized zirconium oxide.

6. (Original) A component according to claim 1 wherein the electroplated coating comprises a thickness having a gradually changing concentration of the yttrium-containing species therethrough.

7. (Currently Amended) A substrate processing chamber comprising:
- (a) a wall around a process zone;
  - (b) a substrate support in the process zone;
  - (c) a ring about the substrate;
  - (d) a gas distributor;
  - (e) a gas energizer; and
  - (f) a gas exhaust port,

wherein at least one of the wall, substrate support, ring, or gas distributor, comprises a component capable of being exposed to a plasma in a process chamber, the component comprising a structure having an electroplated coating comprising yttrium-containing species that is formed by:

- (i) immersing a surface of the structure in an electroplating bath comprising an aqueous solution of yttrium species;
- (ii) connecting the structure to a negative terminal of a voltage source; and
- (iii) connecting an anode immersed in the bath to a positive terminal of the voltage source, and

whereby a substrate transported into the process chamber can be processed by a gas released by the gas distributor, energized by the gas energizer, and exhausted by the gas exhaust port.

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8. (Previously Presented) A chamber according to claim 7 wherein the yttrium-containing species comprises one or more of elemental yttrium and yttrium oxide.

9. (Previously Presented) A chamber according to claim 7 wherein the yttrium-containing species comprises yttrium oxide, and wherein the electroplated coating further comprises aluminum oxide or zirconium oxide.

10. (Previously Presented) A chamber according to claim 7 wherein the electroplated coating comprises a compound comprising yttrium oxide and aluminum oxide.

11. (Previously Presented) A chamber according to claim 7 wherein the electroplated coating comprises partially stabilized zirconium oxide.

12. (Previously Presented) A chamber according to claim 7 wherein the electroplated coating comprises a thickness having a gradually changing concentration of the yttrium-containing species therethrough.

13 – 22. (Cancelled)

23. (Previously Presented) A component according to claim 1 wherein the electroplated coating comprises a thickness having a concentration gradient of yttrium therethrough.

24. (Previously Presented) A component according to claim 1 wherein the electroplated coating comprises a thickness having a concentration gradient of aluminum therethrough.

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25. (Previously Presented) A component according to claim 1 wherein the electroplated coating is fabricated by annealing a first electroplated layer comprising aluminum or zirconium, and a second electroplated layer comprising yttrium.

26. (Previously Presented) A component according to claim 25 comprising annealing the layers to form oxidized species.

27. (Previously Presented) A component according to claim 1 wherein the electroplated coating is fabricated by electroplating a layer comprising a mixture of (i) yttrium and (ii) aluminum or zirconium onto the surface, and annealing the layer.

28. (New) A substrate processing chamber component capable of being exposed to a plasma in a process chamber, the component comprising:

- (a) a substrate processing chamber component structure; and
- (b) an electroplated coating on the substrate processing chamber component structure, the electroplated coating comprising yttrium-containing species and partially stabilized zirconium oxide.

29. (New) A component according to claim 28 wherein the yttrium-containing species comprises one or more of elemental yttrium and yttrium oxide.

30. (New) A component according to claim 28 wherein the yttrium-containing species comprises yttrium oxide, and wherein the electroplated coating further comprises aluminum oxide.

31. (New) A component according to claim 28 wherein the electroplated coating comprises a compound comprising yttrium oxide and aluminum oxide.

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32. (New) A component according to claim 28 wherein the electroplated coating comprises a thickness having a gradually changing concentration of the yttrium-containing species therethrough.

33. (New) A component according to claim 28 comprising a chamber wall, substrate support, ring, or gas distributor, of a process chamber.

34. (New) A component according to claim 1 wherein the anode comprises an inert material or the material to be electroplated.

35. (New) A component according to claim 1 wherein the electroplating bath comprises a yttrium containing electrolyte.

36. (New) A chamber according to claim 7 wherein the anode comprises an inert material or the material to be electroplated.

37. (New) A chamber according to claim 7 wherein the electroplating bath comprises a yttrium containing electrolyte.